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Serial No. 09/879,724

Supplemental Amendment to Office Action Dated August 19, 2003

Attorney Docket No. F0522

Supplemental Amendment Dated November 5, 2003

Firm Reference No. AMDSP0414US

CERTIFICATE OF MAILING OR FACSIMILE TRANSMISSION UNDER 37 CFR 1.8(a)

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 Ahmed N. Sefer.

Linda McElroy
Linda McElroy

November 5, 2003
Date

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of:

Applicant: Dong-Hyuk Ju et al

Art Unit: 2826

Serial No: 09/879,724

Examiner: Ahmed N. Sefer

Filing Date: June 12, 2001

Confirmation No: 4898

Title: **LEAKY, THERMALLY CONDUCTIVE INSULATOR MATERIAL (LTCIM) IN SEMICONDUCTOR-ON-INSULATOR (SOI) STRUCTURE**

Mail Stop AF: Expedited Procedure
 Commissioner for Patents
 P.O. Box 1450
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SUPPLEMENTAL AMENDMENT TO OFFICE ACTION DATED AUGUST 19, 2003

Dear Sir

Favorable reconsideration of the above-identified application is respectfully requested in view of the following amendments and comments. It is believed that the amendments contained

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herein raise no new issues, do not require an additional search and place the application in a better condition for allowance and/or appeal. Accordingly, entry of the amendment is considered proper.

Amendments in the Claims are reflected in the listing of claims that begins on page 3 of this paper.

Remarks begin on page 6 of this paper.